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REMARKS

This Amendment is in response to the Final Office Action of November 4, 2003. Applicants respond to the Final Office Action as follows.

Response to Objection to the Specification

The specification was objected to because "it is not clear from the specification if the method steps claimed in claims 18, 21 and 26 refer to conventional (previous) practices" as described on page 6, lines 18-24 of the specification or to preferred embodiments. As described on page 6, lines 18-24:

Under previous practices for slider/glide head production, one of the cut surfaces of the slider formed from a wafer is formed into the air-bearing surface. If a cut surface is formed into the air bearing surface, a thermal transducer formed along an edge of the slider can be placed on the wafer prior to cutting the slider from the wafer.

Thus as described on page 6, lines 18-24 with respect to previous practices, transducers are formed on the wafer prior to cutting and the air bearing surfaces are formed on cut surfaces of the wafer to form the transducer along an edge of the slider.

Claims 18 and 21 relate to a fabrication method reciting *inter alia* the steps of slicing a plurality of glide bodies from a wafer and depositing thermal transducer on the plurality of glide bodies sliced from the wafer in contrast to the conventional practice described on page 6, lines 18-24 of Applicants' specification of fabricating or forming the transducer prior to cutting. Claims 18 and 21 recite depositing thermal transducers on a plurality of glide bodies sliced from the wafer which is fully supported by or described in Applicants' specification at page 14, lines 4-16.

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Claim 26 relates to a fabrication method where the **bearing surfaces and transducer** are formed on the wafer prior to cutting or slicing the wafer in contrast to previous practices described on page 6, lines 18-27 where the transducer is deposited or formed on the wafer prior to cutting and the air bearing surfaces are formed after the wafer is cut or formed on a cut surface of the wafer as described at page 6, lines 18-24. Fabrication of the bearing surface(s) and transducer at the wafer level is described in Applicants' specification at page 14, lines 23-26. Based upon the foregoing withdrawal of the objections to the specification are respectfully requested.

The specification was objected to on the basis of the claim limitation "contoured disc facing surface" and "thickness portion forming a contoured profile of the contoured disc facing surface". Claims 2, 16 and 28 have been amended to recite contoured surface which is fully supported by Applicants' specification, page 7, lines 19-21 and page 13, lines 17-22 and page 14, lines 10-14 and to recite a thickness portion forming a profile 518 of the contoured surface. The specification and FIG. 10 as amended clarifies recitation of a thickness portion forming a profile of the contoured surface as recited in the claims. Based upon the foregoing withdrawal of the objection to the specification as recited above is respectfully requested.

Response to Objection to the Drawings

The drawings were objected to on the basis that the drawings do not show a "contoured disc facing surface" and the "thickness portion forming a contour profile of the contoured disc facing surface of the glide body". As amended claims recite a contoured surface and a thickness portion forming a profile 518 of the contoured surface as illustrated in amended FIG. 10. Reconsideration and withdrawal of the objection to the drawings are respectfully requested.

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Response to Claim Rejections - 35 U.S.C. § 112

Claims 2, 16, 18, 21, 26 and 28 were rejected under 35 U.S.C. § 112, first paragraph as containing subject matter which was not described in the specification in such a way as to enable one skilled in the art to which it pertains to make and /or use the invention. Claim 18 and 21 recite *inter alia* the steps of slicing a plurality of glide bodies from a wafer and depositing thermal transducers on the plurality of glide bodies sliced from the wafer. Claims 18 and 21 were rejected as best understood on the basis that "it is not clear from the specification whether the method of placing the transducer onto the wafer **prior to slicing** is conventional" as disclosed at page 6, lines 18-27. Claims 18 and 21 recite *inter alia* the steps of depositing a thermal transducers after cutting or slicing not fabrication of transducers prior to slicing or at the wafer level as disclosed at page 6, lines 18-27. Support for claims 18 and 21 is found at page 14, lines 4-16 of Applicants' specification.

Claim 26 recites *inter alia* a method of fabrication including the steps of fabricating a raised bearing surface and a recessed bearing surface and depositing or fabricating thermal transducers at the wafer level prior to slicing glide heads from the wafer which is disclosed in Applicants' specification at page 14, lines 17-28 and FIG. 8. As best understood the specification was objected to on the basis that page 6, lines 18-27 disclose previous practices of placing transducers on the wafer prior to cutting without consideration of each of the claim limitations including **both** fabricating transducers **and** air bearing surfaces prior to cutting or slicing as disclosed on page 14, lines 17-28 and thus withdrawal of the objection is respectfully requested.

Claims 2, 16, and 28 were rejected on the basis that the thickness portion forming a contour profile of the contoured disc facing surface of the glide body has not been described in the specification. As discussed above, the recited subject matter of

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the amended claims is fully supported by Applicants' specification.

Claims 2, 16, 18, 20, 26, 28, and 4-7, 9-14, 20-21, 23-24, 29 were rejected under 35 U.S.C. § 112, second paragraph on the basis that the claim language is confusing as stated in paragraph 5 of the Office Action. Paragraph 5 rejected claims on the basis that it is unclear whether placing the transducer on the wafer prior to slicing is conventional and for the reasons set forth above is improper and should be withdrawn.

Response to Claim Objections

Claims 2, 4-5, 21, 27-28 were objected to because the preamble of the claims dependent upon claim 2 should be replaced with --The glide test system--. Claims 4-5 are dependent upon claim 28, claim 21 is dependent upon claim 18 and claims 27-28 are independent and not dependent upon claim 2 and accordingly withdrawal of the objection to claims 2, 4-5, 21, 27-28 with respect to the preamble is respectfully requested.

Claim 2, 28 were objected to on the basis of the claim language "contoured disc facing surface" which as discussed above has been amended and as amended is disclosed in Applicant's specification as discussed above. Recitation of air bearing in claim 21 has been amended to recite air bearing surfaces.

Claim 27 was objected to on the basis that the at least one bond pad lacks antecedent basis and it was not clear whether the claim was amended. Applicants have corrected the informalities with respect to claim 27.

Response to Claim Rejections - 35 U.S.C. § 102

Claims 2, 4-6, 10-11, 14, 16, 20, 23, 25-29 were rejected under 35 U.S.C. § 102(e) as being anticipated by Boutaghou, U.S. Patent No. 5,808,184. Claims 2, 4-6, 10-11, 14, 23 and 28 recite *inter alia* a thermal transducer on a raised bearing surface of a glide body including a surface portion along the raised bearing surface and a thickness portion intersecting the surface portion

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and forming a profile of the contoured surface of the glide body. Claim 16 recites *inter alia* fabrication of a glide body including a thermal transducer on a raised bearing surface to form a surface portion providing a glide interface and a thickness portion forming a profile of the air bearing surface. As understood, claims 2, 4-6, 10-11, 14, 16 23 and 28 were rejected on the basis that Boutaghou inherently discloses "the thickness of the transducer is forming a contour profile of the contoured disc facing surface and is intersecting (contacting) with its portion extending along the ABS" on the basis that the added "limitation has not been shown in the drawings or clearly described in the specification". Applicants have amended the specification to clarify the structure of the added limitation and respectfully request reconsideration and withdrawal of the rejection of claims 2, 4-6, 10-11, 14, 16, 23 and 28 based upon the amended specification and FIGS.

Claim 26 is dependent upon claim 16 and further recites *inter alia* that the fabrication of the raised bearing surface and the recessed surface and the deposition or fabrication of a thermal transducer is performed on a surface of a wafer prior to slicing the wafer. Claim 26 was rejected on the basis that Boutaghou discloses that the transducers are fabricated at the wafer level (Col. 3, line 22) prior to slicing without consideration of each of the claim limitation including fabrication of the air bearing surface and transducer at the wafer level and therefore the Office Action fails to provide a *prima facie* basis to reject claim 26.

Claim 29 is dependent upon claim 16 and further recites *inter alia* that the air bearing surface is fabricated prior to the step of depositing the thermal transducer on the raised bearing surface. Claim 29 was rejected on the basis that "it is inherent that the ABS must be fabricated prior to depositing the thermal transducers onto it and thus, onto the raised bearing

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surface of the ABS" However, as described in Applicants' specification on page 6, lines 18-24 if the thermal transducer is deposited at the wafer level prior to slicing one of the cut surfaces is formed into the air bearing surface or after cutting or slicing. Since the ABS is formed on a cut surface after cutting or slicing it is not inherent that the ABS must be fabricated prior to depositing the thermal transducer. Page 14, lines 4-16 describe contouring the air bearing surface following cutting **and** following contouring fabricating the thermal transducers in contrast to fabricating the transducer at the wafer level prior to cutting and forming the air bearing from a cut edge of the wafer as in previous practices described on page 6, lines 18-24, page 13, lines 30-32. Based upon the foregoing the Office Action fails to establish that it is inherent that the ABS must be fabricated prior to depositing the thermal transducer since the transducer can be deposited at the wafer level and the ABS contoured on a cut surface of the wafer after slicing or cutting as described on page 6, lines 18-24 and page 13, lines 30-32.

Claim 25 is a means-plus-function claim which recites *inter alia* an asperity detection means on the glide body for detecting asperities. Means-plus-function limitations in a claim are interpreted to include the corresponding structure disclosed in the specification and equivalents. Claim 25 was rejected without reference to the corresponding structure disclosed in the specification and equivalents. Reconsideration and allowance of claim 25 are respectfully requested.

Rejected claim 27 has been amended clarify the status of the added claim limitation. Reconsideration and allowance of claim 27 with the added claim limitation are respectfully requested.

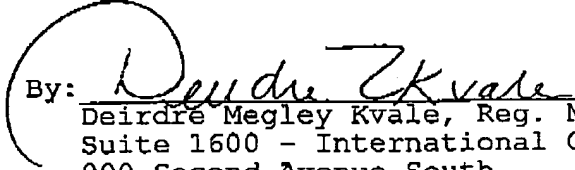
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The Director is authorized to charge any fee deficiency required by this paper or credit any overpayment to Deposit Account No. 23-1123.

Respectfully submitted,

WESTMAN, CHAMPLIN & KELLY, P.A.

By:


Deirdre Megley Kvale, Reg. No. 35,612
Suite 1600 - International Centre
900 Second Avenue South
Minneapolis, Minnesota 55402-3319
Phone: (612) 334-3222 Fax: (612) 339-3312

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